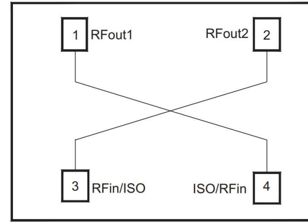
Performance

- Frequency: 0.8~2.0GHz
- Insertion loss: 1.5dB
- Chip size: 1.8*1.0*0.1mm

Function Diagram

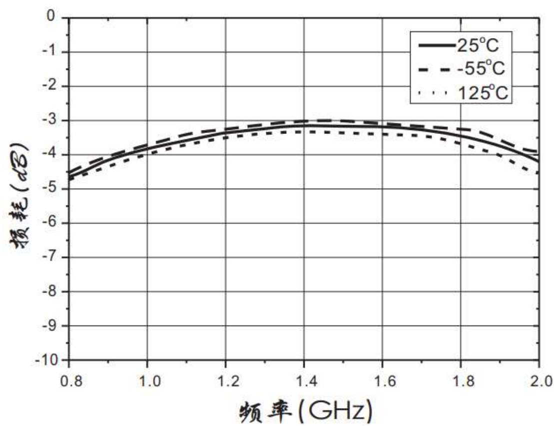


Electrical Specifications (Ta=+25℃, 50Ω system)

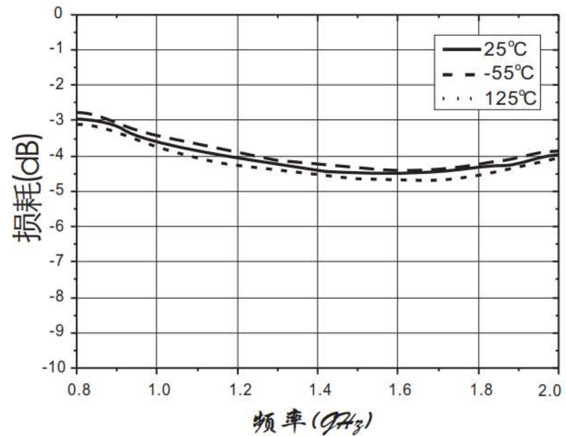
Parameter	Min	Typical	Max	Unit
Frequency Range	0.8~2.0			GHz
Insertion Loss	-	1.5	-	dB
Input Return loss	20	23	-	dB
Output Return loss	17	23	-	dB
Isolation	18	23	-	dB
Amplitude Balance	-	±1.0	-	dB
Phase Balance	-	±6.0	-	Deg

Test Curves (Die chip + Bonding line test)

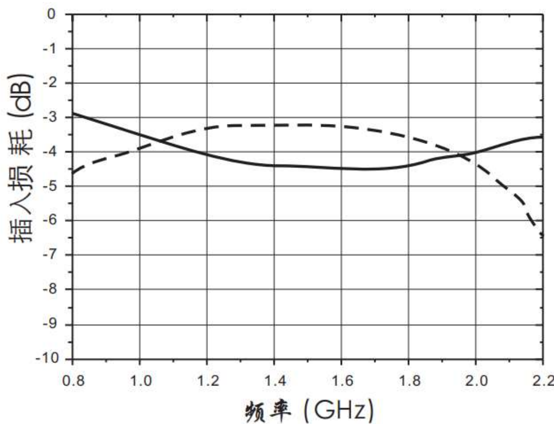
Insertion loss vs. Freq



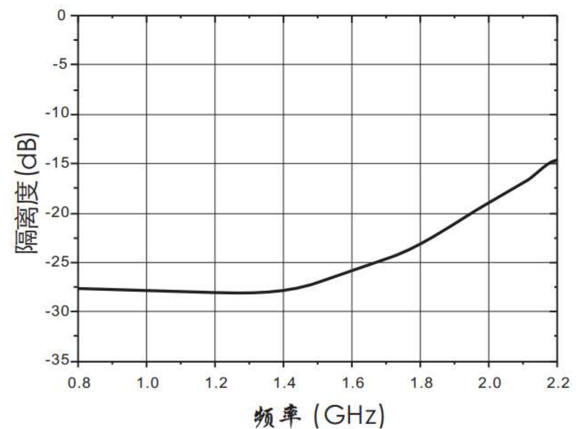
Insertion loss vs. Freq



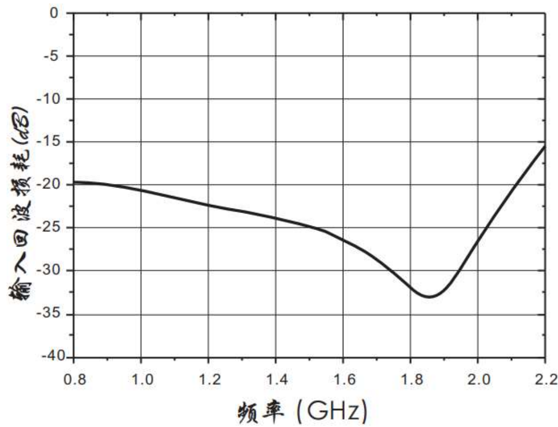
Insertion loss vs. Freq



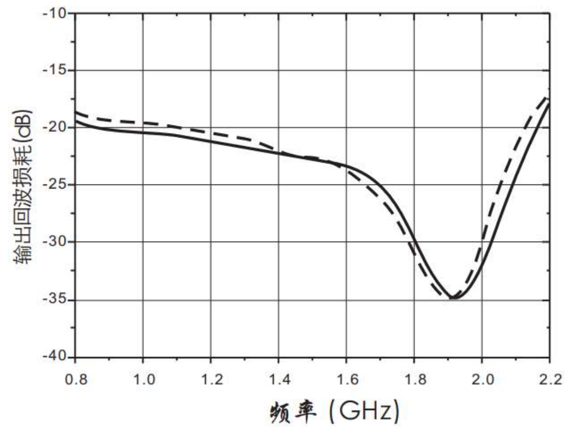
Isolation vs. Freq



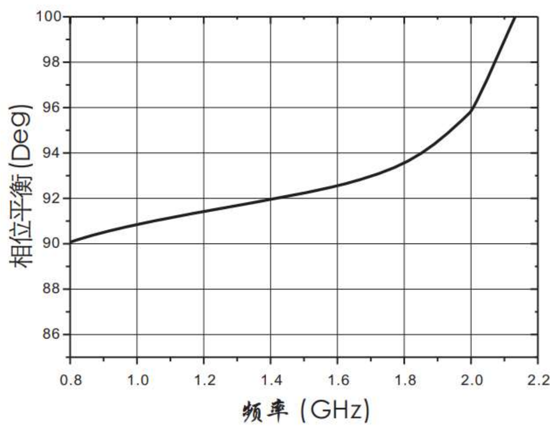
Input Return Loss vs. Freq



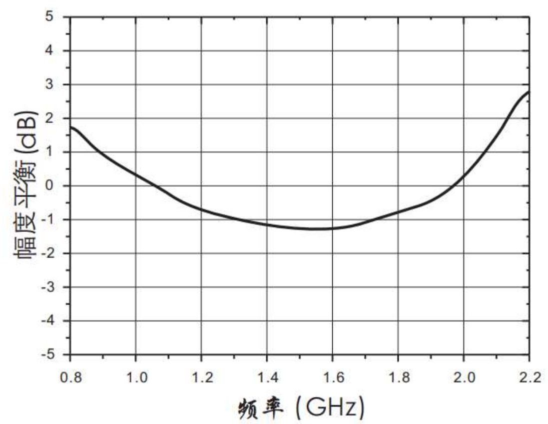
Output Return Loss vs. Freq



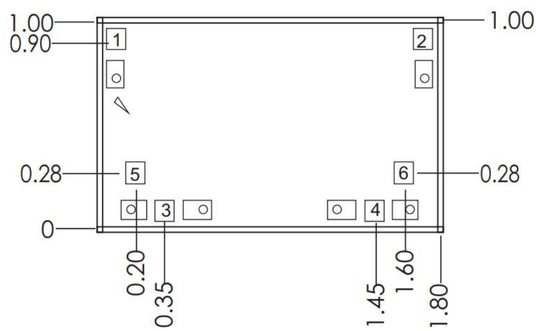
Phase Balance vs. Freq



Amplitude Balance vs. Freq



Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, size: 100*100(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um

Bonding Pads Definition

Number	Symbol	Description
1,2	RFout 1, RFout2	RF output port, 50ohm
3,4	RFin/ISO	Choose either one as input, another port is connected to 50ohm resistor pads
5,6	Load	50ohm resistor pads
	GND	Bottom must be GND

Absolute Max Ratings

Max Input Power	+27dBm
Static Class	Class 1A
Storage Temperature	-65 ~ +150℃
Operating Temperature	-55 ~ +125℃

Note: For high power application, assemble with Eutectic sintering.

Application